

PRODUCT DATA SHEET



ECOREL FREE 808.3-85

Low residue LEAD FREE solder paste
No clean - High melting point
Application by automatic dispensing systems



ECOREL FREE 808.3-85 solder paste has been developed by PROMOSOL, for application by dots with a no-clean process. It can be reflowed under air, nitrogen or in vapour phase with a wide process window.

<u>SPECIFICATIONS</u>	<u>According to C 90 550 IPC TM 650</u>	
Alloy	Sn96 Ag	
Powder size distribution	25 - 45	
Melting point (°C)	221	
Metal content (%)	85	
Residue after reflow soldering (%)	50	
Acid index on organic part (mg KOH/g)	103	
Halogen content (%)	0	
Viscosity* (Pa.s 20°C) *Brookfield RVT - TF at 5 rpm.	400	
<u>FUNCTIONAL TESTS</u>	<u>NORM</u>	
Flux classification	FC L0 F-SW 32 113	C 90550 ANSI/J-STD-004 DIN 8511 ISO 9454
Solderballing test	Class 1	C 90550
Copper mirror	pass	ANSI-J-STD-004
Chromate paper	pass	ANSI-J-STD-004
Copper corrosion	pass	ANSI-J-STD-004
Surface Insulation Resistance OHMS		ANSI-J-STD-004
After 21 days		
85°C - 85 % RH - 50 Volts	> 10 ¹⁰	
25°C - 65 % RH	> 10 ¹²	



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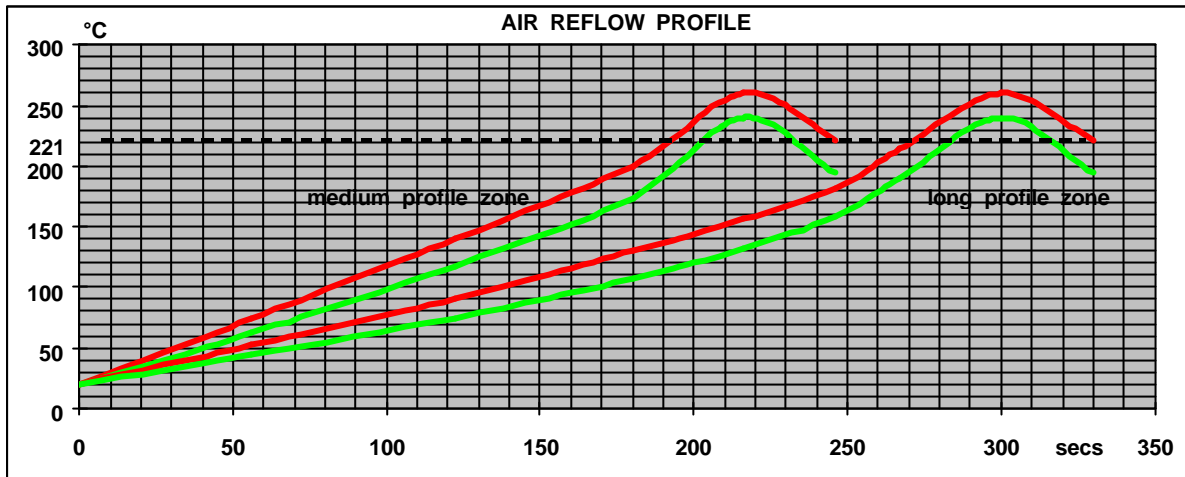
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REFLOW THERMAL PROFILE

The under graph indicates, according to thermal mass of PCB and mounted components, the optimal profile zone which have to be respected to obtain a good reflow under air without solderball.



By using a nitrogen atmosphere, you can enlarge your process window towards reflow thermal profile. This permits better wetting and coalescence.

A regular preheat temperature rise is preferable to a too long plateau, in order to avoid solderbeading to get a shining joint and a uniform residue distribution.

APPLICATION

ECOREL FREE 808.3-85 solder paste is applied by dots with automatic dispensing systems (inner diameter of needles > 0.2 mm).

For surface mounting or rework, it is possible to apply a continuous line of solderpaste, using hot air or nitrogen reflow.

PACKAGING

✦ Syringes : 30 & 75 g.

STORAGE

To ensure the best product performance, the recommended storage temperature range is 5°C to 10°C. A shelf life of 6 months is achieved under these conditions.

Before use, allow several hours at room temperature for the paste to stabilize.

HEALTH AND SAFETY

Please refer to MSDS.

*The information given herewith is designed only as a guidance and is not to be considered warranty of PROMOSOL.
Réf. FPCGB 80835 TSI PRO 02 - 27/04/2000*



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